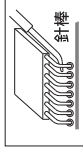
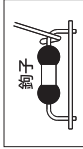


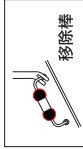
■ 使用方法



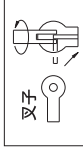
拆下IC等零件時使用。
使用焊鐵將焊錫熔化後
讓IC的引線凸出然後取
下。



利用焊鐵邊將焊錫熔
化，邊取下在印刷電路
板上安裝的電子零件。



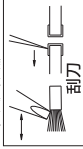
使用焊鐵邊將焊錫熔
化，邊壓住引線然後
拆下電阻，電容器，
IC時用。



為使用彎曲電阻等電子
零件的引線朝向著
印刷電路板上模型。

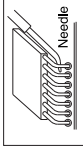


使用於除去焊錫渣滓，
印刷電路板上的屏蔽
墨水以及除鏽。

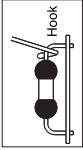


使用於除去引線的皮
膜，印刷電路板上的
屏蔽以及除鏽。

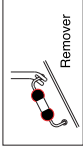
■ OPERATION



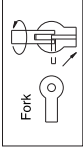
Use for removing electronic
component, such as IC etc.
Using the soldering iron to
melt the solder and lift the
lead wire of IC simultaneously,
and then remove it.



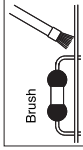
Using the soldering iron to melt
the solder and then use the
hook to remove the electronic
component on the P.W.B.



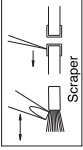
Removing the resistance, con-
denser and IC by using the
soldering iron to melt the solder
and use the remover to hold its
lead wire to remove.



Use for bending the electronic
components, such as resistance
toward the direction of the P.W.
B. pattern.

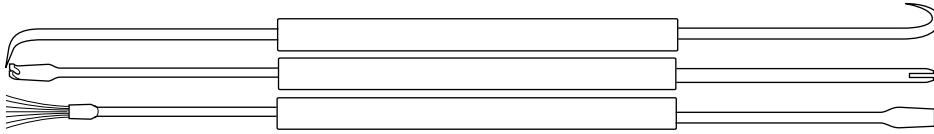


Removing and rubbing solder
dregs and masking ink of the
P.W.B.



Use for removing the film of lead
wire, masking of the P.W.B. and
rubbing the rust of the P.W.B.
etc.

Needle
針棒
Remover
移除棒
Brush
刷子



Hook
鉤子
Fork
叉子
Scraper
刮刀



⚠ CAUTION/ 警告

There are some shape knife in the 600-02 package,
be very carefull when use.

600-02包裝內含有刀具等銳利的工具，
使用時請充分注意。

FEATURES

Easy to use:

- When insert the components,
including chip, axial and radial.
- When remove for cleaning etc.

特點

可使用於：

- 當安裝電子零件，
軸的零件及豎零件時。
- 當拆下零件時清理等。

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